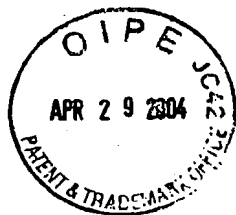


DOCKET NO.: H 3516 PCT/US HENK-0022
Application No.: 09/807,948
Office Action Dated: March 2, 2004

PATENT
REPLY FILED UNDER EXPEDITED
PROCEDURE PURSUANT TO 37 CFR §1.116



OK to Enter

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

QW

5/6/04

In re Application of:
Ranft et al.

Confirmation No.: 9265

Application No.: 09/807,948

Group Art Unit: 1733

Filing Date: November 27, 2001

Examiner: John L. Goff II

For: Hot-Melt Adhesive Component Layers For Smart Cards

EXPRESS MAIL LABEL NO: EL998517428US
DATE OF DEPOSIT: April 29, 2004

Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

REPLY PURSUANT TO 37 CFR § 1.116

In response to the Official Action dated March 2, 2004, reconsideration is respectfully requested in view of the amendments and/or remarks as indicated below:

- ☐ Amendments to the Specification begin on page of this paper.
- ☐ Amendments to the Claims are reflected in the listing of the claims which begins on page of this paper.
- ☐ Amendments to the Drawings begin on page of this paper and include an attached replacement sheet.
- ☒ Remarks/Arguments begin on page 2 of this paper.